

18-Line Low Capacitance SCSI Active Terminator

FEATURES

- Complies with SCSI, SCSI-2 and SPI-2 Standards
- 6pF Channel Capacitance during Disconnect
- 100μA Supply Current in Disconnect Mode
- Meets SCSI Hot Plugging Capability
- –650mA Sourcing Current for Termination
- +200mA Sinking Current for Active Negation
- Provides Active Termination for 18 Lines
- Logic Command Disconnects all Termination Lines
- Trimmed Termination Current to 5%
- Trimmed Impedance to 5%
- Current Limit and Thermal Shutdown Protection

DESCRIPTION

The UC5608 provides 18 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the bus cable.

The UC5608 is pin-for-pin compatible with its predecessors, the UC5601 and UC5602 - 18 Line Active Terminator. Parametrically the UC5608 has a 5% tolerance on impedance and current compared to a 3% tolerance on the UC5601 and the sink current is increased from 20 to 200mA. The low side clamps have been removed. Custom power packages are utilized to allow normal operation at full power conditions (2 Watts).

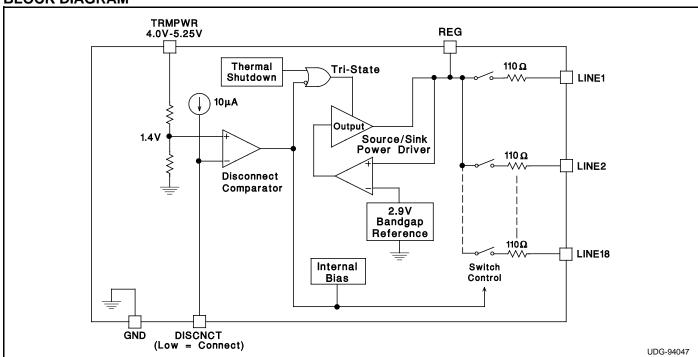
When in disconnect mode the terminator will disconnect all terminating resistors and disable the regulator, greatly reducing standby power. The output channels remain high impedance even without Termpwr applied.

Internal circuit trimming is utilized to trim the impedance to a 5% tolerance and, most importantly, to trim the output current to a 5% tolerance, as close to the max SCSI spec as possible, which maximizes noise margin in fast SCSI operation.

Other features include 4.0 to 5.25V Termpwr, thermal shutdown and current limit.

This device is offered in low thermal resistance versions of the industry standard 28 pin wide body SOIC, 28 pin wide body TSSOP, and 28 pin PLCC, as well as 24 pin DIP.

BLOCK DIAGRAM



Circuit Design Patented

ABSOLUTE MAXIMUM RATINGS

Termpwr Voltage	+7V
Signal Line Voltage	0V to +7V
Regulator Output Current	1A
Storage Temperature	to +150°C
Operating Temperature	
Lead Temperature (Soldering, 10 Sec.)	+300°C

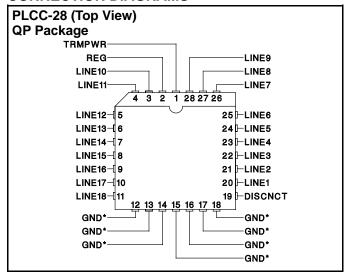
Unless otherwise specified all voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal.

Consult Packaging Section of Unitrode Integrated Circuits databook for thermal limitations and considerations of packages.

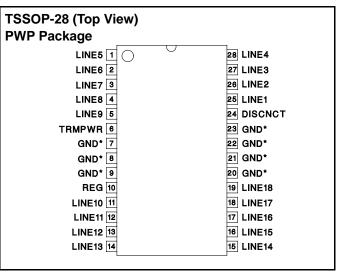
RECOMMENDED OPERATING CONDITIONS

Termpwr Voltage	3.8V to 5.25V
Signal Line Voltage	0V to +5V
Disconnect Input Voltage	0V to Termpwr

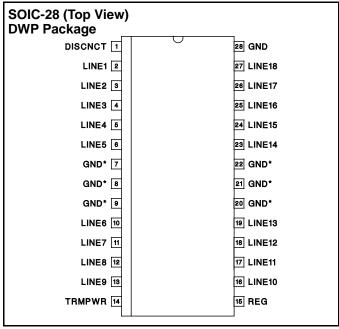
CONNECTION DIAGRAMS



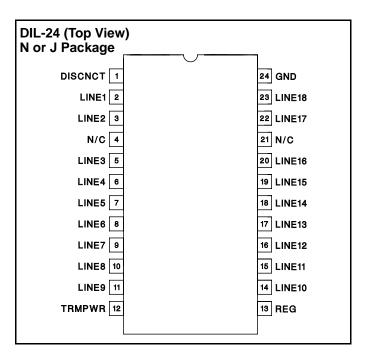
* QP package pins 12 - 18 serve as both heatsink and signal ground.



* PWP package pin 23 serves as signal ground; pins 7, 8, 9, 20, 21 and 22 serve as heatsink/ground.



* DWP package pin 28 serves as signal ground; pins 7, 8, 9, 20, 21, 22 serve as heatsink/ground.



Note: Drawings are not to scale.

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for TA = 0°C to 70°C. TRMPWR = 4.75V, DISCNCT = Ground. TA = TJ.

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNITS			
Supply Current Section										
Termpwr Supply Current	All termination lines = Open				17	25	mΑ			
	All termination lines = 0.5V				400	430	mA			
Power Down Mode	DISCNCT = Open				100	150	μΑ			
Output Section (Terminator Lines)										
Terminator Impedance	Δ ILINE = -5mA to -15mA			104.5	110	115.5	Ohms			
Output High Voltage	VTRMPWR = 4V (Note 1)			2.65	2.9	3.0	V			
Max Output Current	VLINE = $0.5V$ TJ = $25^{\circ}C$		TJ = 25°C	-20.3	-21.5	-22.4	mA			
		0°C		-19.8	-21.5	-22.4	mΑ			
Max Output Current	VLINE = 0.5V, TR	VLINE = 0.5V, TRMPWR = 4V (Note 1)		-19.5	-21.5	-22.4	mA			
				-19.0	-21.5	-22.4	mA			
	VLINE = 0.2V, TR	MPWR = 4V to 5.25V	0°C < TJ < 70°C	-21.6	-24.0	-25.4	mA			
Output Leakage	DISCNCT = 4V	TRMPWR = 0V to 5.25V REG = 0V	VLINE = 0 to 4V		10	400	nA			
			VLINE = 5.25V			100	μΑ			
		TRMPWR = $0V$ to $5.25V$,	REG = Open		10	400	nA			
		VLINE = 0V to 5.25V								
Output Capacitance	DISCNCT = Open (Note 2)				6	7	pF			
Regulator Section										
Regulator Output Voltage					2.9	3	V			
Regulator Output Voltage	All Termination Lines = 4V		2.8	2.9	3	V				
Line Regulation	TRMPWR = 4V to 6V			10	20	mV				
Drop Out Voltage	All Termination Lines = 0.5V			1.0	1.2	V				
Short Circuit Current	VREG = 0V		-450	-650	-950	mA				
Sinking Current Capability	VREG = 3.5V		100	200	500	mA				
Thermal Shutdown					170		°C			
Thermal Shutdown Hysteresis					10		°C			
Disconnect Section										
Disconnect Threshold				1.1	1.4	1.7	V			

Note 1: Measuring each termination line while other 17 are low (0.5V).

Note 2: Guaranteed by design. Not 100% tested in production.

APPLICATION INFORMATION

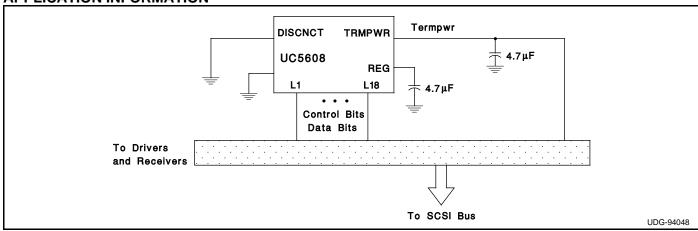


Figure 1: Typical SCSI Bus Configuration

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1999, Texas Instruments Incorporated